



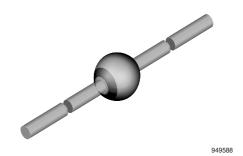
Fast Avalanche Sinterglass Diode

Features

- · Glass passivated
- · Hermetically sealed package
- · Very low switching losses
- Low reverse current
- · High reverse voltage

Applications

Switched mode power supplies High-frequency inverter circuits



Mechanical Data

Case: Sintered glass case, SOD 64

Terminals: Plated axial leads, solderable per

MIL-STD-750, Method 2026

Polarity: Color band denotes cathode end

Mounting Position: Any

Weight: 860 mg, (max. 1000 mg)

Parts Table

Part	Type differentiation	Package
ВҮМ36А	V _R = 200 V; I _{FAV} = 3 A	SOD64
ВҮМ36В	V _R = 400 V; I _{FAV} = 3 A	SOD64
ВҮМ36С	V _R = 600 V; I _{FAV} = 3 A	SOD64
BYM36D	V _R = 800 V; I _{FAV} = 2.9 A	SOD64
BYM36E	V _R = 1000 V; I _{FAV} = 2.9 A	SOD64

Absolute Maximum Ratings

 T_{amb} = 25 °C, unless otherwise specified

Parameter	Test condition	Sub type	Symbol	Value	Unit
Reverse voltage = Repetitive peak reverse	see electrical characteristics	BYM36A	V _R =	200	V
voltage			V_{RRM}		
	see electrical characteristics	BYM36B	V _R =	400	V
			V_{RRM}		
	see electrical characteristics	BYM36C	V _R =	600	V
			V_{RRM}		
	see electrical characteristics	BYM36D	V _R =	800	V
			V_{RRM}		
	see electrical characteristics	BYM36E	V _R =	1000	V
			V_{RRM}		
Peak forward surge current	t _p = 10 ms, half sinewave		I _{FSM}	65	Α



Parameter	Test condition	Sub type	Symbol	Value	Unit
Average forward current		BYM36A- BYM36C	I _{FAV}	3	Α
		BYM36D- BYM36E	I _{FAV}	2.9	Α
Non repetitive reverse avalanche energy	I _{(BR)R} = 1 A, inductive load		E _R	20	mJ
Junction and storage temperature range			$T_j = T_{stg}$	- 55 to + 175	°C

Maximum Thermal Resistance

 T_{amb} = 25 °C, unless otherwise specified

Parameter	Test condition	Sub type	Symbol	Value	Unit
Junction ambient	I = 10 mm, T _L = constant		R _{thJA}	25	K/W
	on PC Board with spacing 25 mm		R _{thJA}	70	K/W

Electrical Characteristics

T_{amb} = 25 °C, unless otherwise specified

Parameter	Test condition	Sub type	Symbol	Min	Тур.	Max	Unit
Forward voltage	I _F = 3 A	BYM36A- BYM36C	V _F			1.6	V
	I _F = 3 A	BYM36D- BYM36E	V _F			1.78	V
	I _F = 3 A, T _j = 175 °C	BYM36A- BYM36C	V _F			1.22	V
	I _F = 3 A, T _j = 175 °C	BYM36D- BYM36E	V _F			1.28	V
Reverse current	$V_R = V_{RRM}$		I _R			5	μΑ
	$V_R = V_{RRM}$, $T_j = 150$ °C		I _R			100	μΑ
Reverse breakdown voltage	I _R = 100 μA	BYM36A	V _{(BR)R}	300			V
	I _R = 100 μA	BYM36B	V _{(BR)R}	500			V
	I _R = 100 μA	ВҮМ36С	V _{(BR)R}	700			V
	I _R = 100 μA	BYM36D	V _{(BR)R}	900			V
	I _R = 100 μA	BYM36E	V _{(BR)R}	1100			V
Reverse recovery time	$I_F = 0.5 \text{ A}, I_R = 1 \text{ A}, i_R = 0.25 \text{ A}$	BYM36A- BYM36C	t _{rr}			100	ns
	$I_F = 0.5 \text{ A}, I_R = 1 \text{ A}, i_R = 0.25 \text{ A}$	BYM36D- BYM36E	t _{rr}			150	ns

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Typical Characteristics ($T_{amb} = 25$ °C unless otherwise specified)

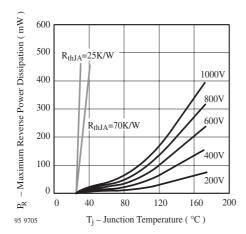


Figure 1. Max. Reverse Power Dissipation vs. Junction Temperature

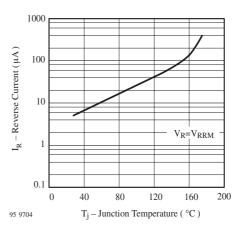


Figure 4. Max. Reverse Current vs. Junction Temperature

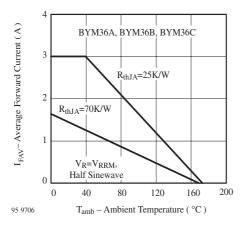


Figure 2. Max. Average Forward Current vs. Ambient Temperature

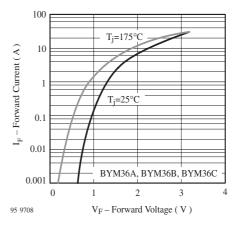


Figure 5. Max. Forward Current vs. Forward Voltage

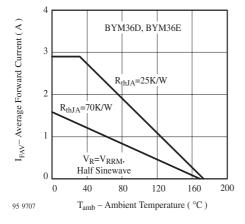


Figure 3. Max. Average Forward Current vs. Ambient Temperature

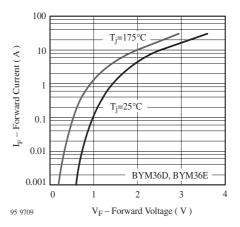


Figure 6. Max. Forward Current vs. Forward Voltage



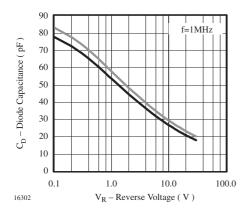
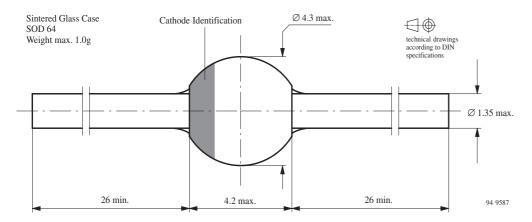


Figure 7. Diode Capacitance vs. Reverse Voltage

Package Dimensions in mm





Ozone Depleting Substances Policy Statement

It is the policy of Vishay Semiconductor GmbH to

- 1. Meet all present and future national and international statutory requirements.
- 2. Regularly and continuously improve the performance of our products, processes, distribution and operatingsystems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

- 1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
- 2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
- 3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design and may do so without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use Vishay Semiconductors products for any unintended or unauthorized application, the buyer shall indemnify Vishay Semiconductors against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

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